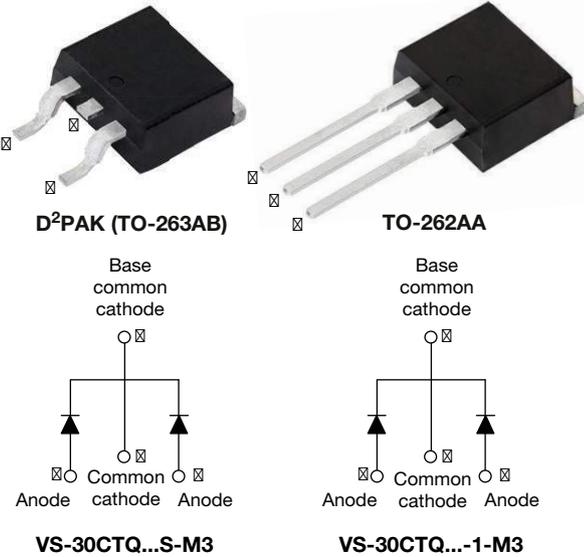




High Performance Schottky Rectifier, 2 x 15 A



FEATURES

- Center tap operation
- Center tap configuration
- Very low forward voltage drop
- High frequency operation
- High purity: high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level: per J, STD; LFL maximum peak of 100°C
- Designed and qualified according to JEDEC®; JESD
- Material categorization for definitions of compliance please see www.vishay.com/doc?

RoHS
COMPLIANT
HALOGEN
FREE

DESCRIPTION

This center tap Schottky rectifier has been optimized for very low forward voltage drop with moderate leakage. The proprietary barrier technology allows for reliable operation up to 100°C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

| PRIMARY CHARACTERISTICS | |
|-------------------------|---|
| I_{FAV7} | 15 A |
| V_R | 100 V / 150 V |
| $V_{F@tF}$ | 0.45 V |
| $I_{RM}^{typ}<$ | 10 mA at 100°C |
| $T_{jmax}<$ | 100°C |
| E_{AS} | 10 mJ |
| Package | D ² PAK (TO-263AB); TO-262AA |
| Circuit configuration | Common cathode |



| ABSOLUTE MAXIMUM RATINGS | | | | | |
|--|-------------|---|---|----------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | VALUES | UNITS |
| Maximum average forward current See Fig. 4-10 | $I_{F(AV)}$ | τ Duty cycle at T_C : Rectangular waveform | | ∞ | A |
| | | | | ∞ | |
| Maximum peak one cycle non-repetitive surge current See Fig. 4-11 | I_{FSM} | μ s sine or μ s rect pulse | Following any rated load condition and with rated V_{RRM} applied | ∞ | A |
| | | μ s sine or μ s rect pulse | | ∞ | |
| Non-repetitive avalanche energy | E_{AS} | T_J : T_C ; I_{AS} : I_{AS} ; dI/dt : ∞ mH | | ∞ | mJ |
| Repetitive avalanche current | I_{AR} | Current decaying linearly to zero in μ s Frequency limited by T_J maximum V_{AR} < V_{RRM} typical | | ∞ | A |

| ELECTRICAL SPECIFICATIONS | | | | | |
|---|--------------------|--|---------------------|----------|------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | VALUES | UNITS |
| Maximum forward voltage drop See Fig. 4-12 | V_{FM}^{67} | ∞ A | T_J : ∞ C | ∞ | V |
| | | ∞ A | | ∞ | |
| | | ∞ A | T_J : ∞ C | ∞ | |
| | | ∞ A | | ∞ | |
| Maximum reverse leakage current | I_{RM}^{67} | T_J : ∞ C | V_R : Rated V_R | ∞ | mA |
| | T_J : ∞ C | ∞ | | | |
| Typical reverse leakage current | I_{RM} | T_J : ∞ C | V_R : Rated V_R | ∞ | mA |
| Threshold voltage | V_{FO7} | T_J : T_J maximum | | ∞ | V |
| Forward slope resistance | r_t | | | ∞ | m Ω |
| Maximum junction capacitance | C_T | V_R : ∞ V/DC; Test signal range: ∞ kHz to ∞ MHz; T_C : ∞ C | | ∞ | pF |
| Typical series inductance | L_S | Measured lead to lead ∞ mm from package body | | ∞ | nH |
| Maximum voltage rate of change | dV/dt | Rated V_R | | ∞ | V/ μ s |

Note

⁶⁷ Pulse width ∞ μ s; duty cycle ∞

| THERMAL - MECHANICAL SPECIFICATIONS | | | | | |
|--|-------------------|--------------------------------------|--|--|-----------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | VALUES | UNITS |
| Maximum junction and storage temperature range | T_J ; T_{Stg} | | | ∞ to ∞ | $^{\circ}$ C |
| Maximum thermal resistance: junction to case | R_{thJC} | DC operation | | ∞ | $^{\circ}$ C/W |
| Maximum thermal resistance: junction to case per package | | | | ∞ | |
| Typical thermal resistance: case to heatsink | R_{thCS} | Mounting surface: smooth and greased | | ∞ | |
| Approximate weight | | | | ∞ | g |
| Mounting torque | minimum | | | ∞ | kgf cm lb in |
| | maximum | | | ∞ | |
| Marking device | | Case style D PAK TO; ∞ AB7 | | ∞ CTQ ∞ S ∞ CTQ ∞ S | |
| | | Case style TO; ∞ AA | | ∞ CTQ ∞ ; ∞ ∞ CTQ ∞ ; ∞ | |

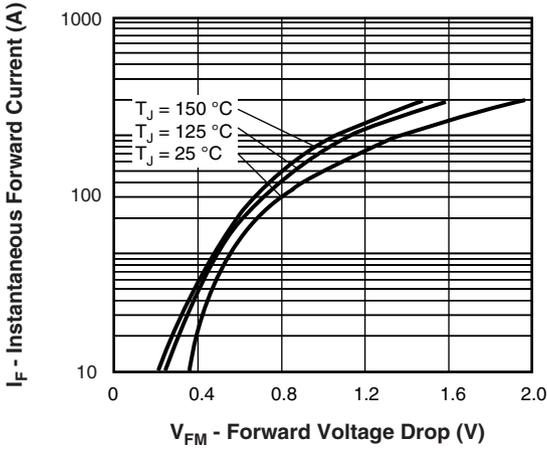


Fig. 4 Maximum Forward Voltage Drop Characteristics Per Leg 7

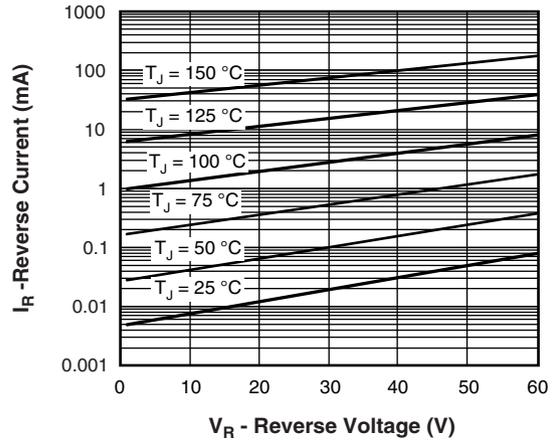


Fig. 5 Typical Values of Reverse Current vs. Reverse Voltage Per Leg 7

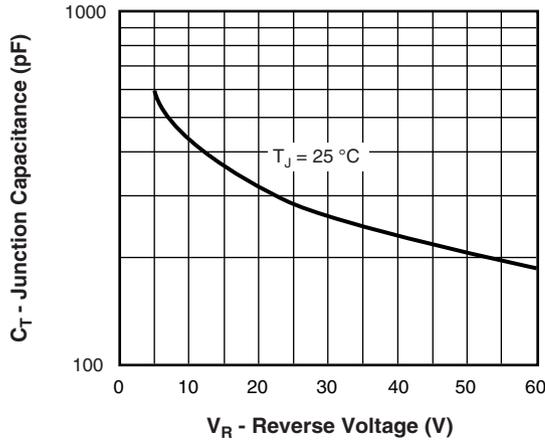


Fig. 6 Typical Junction Capacitance vs. Reverse Voltage Per Leg 7

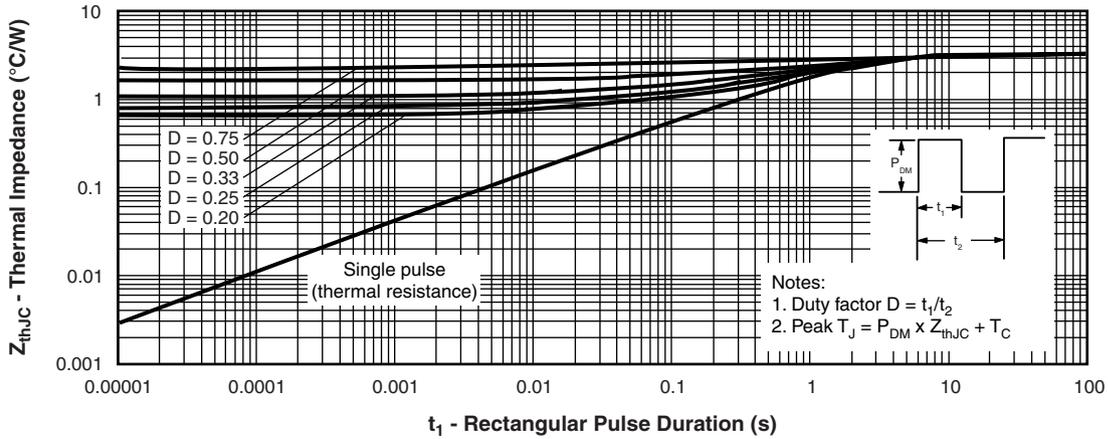
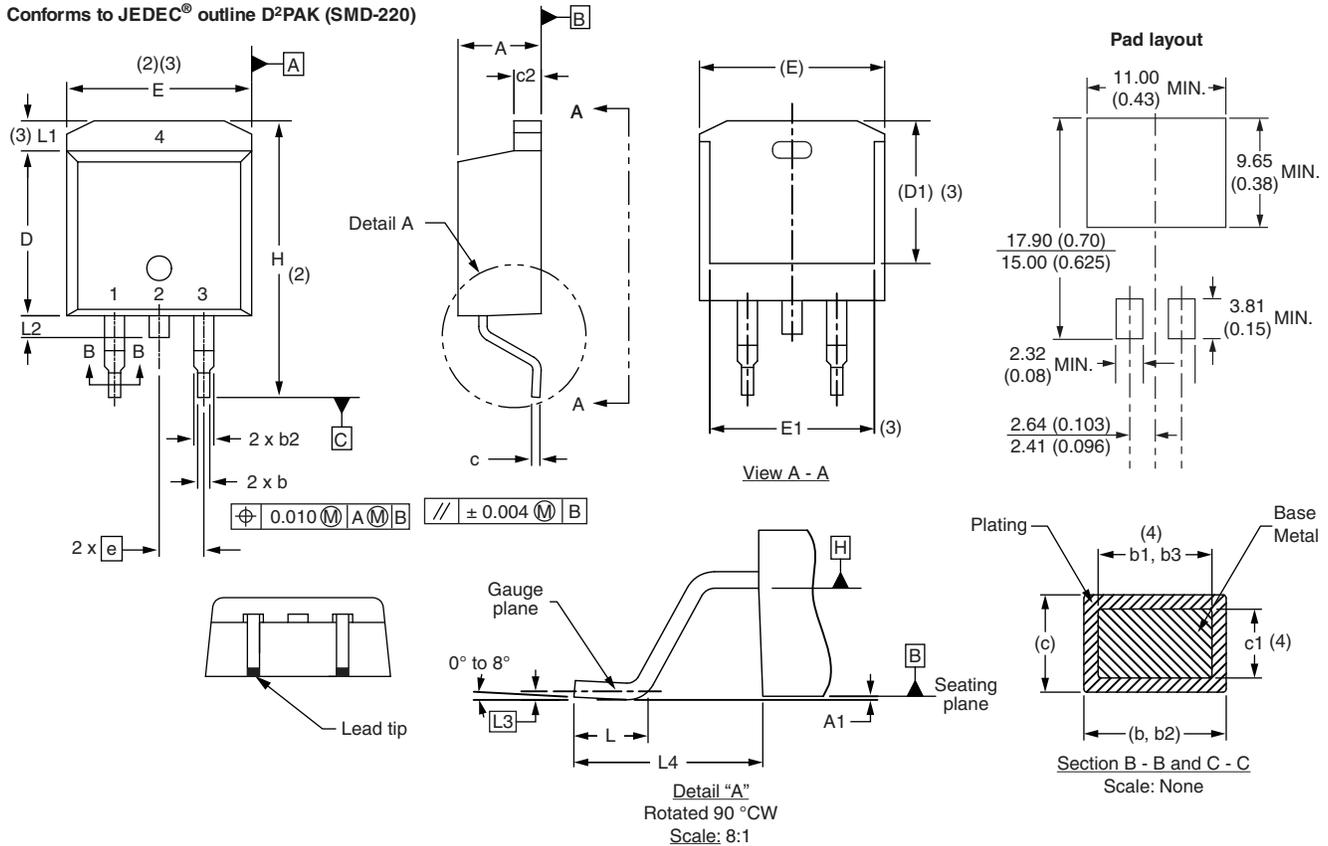


Fig. 7 Maximum Thermal Impedance Z_{thJC} Characteristics Per Leg 7

D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC[®] outline D²PAK (SMD-220)



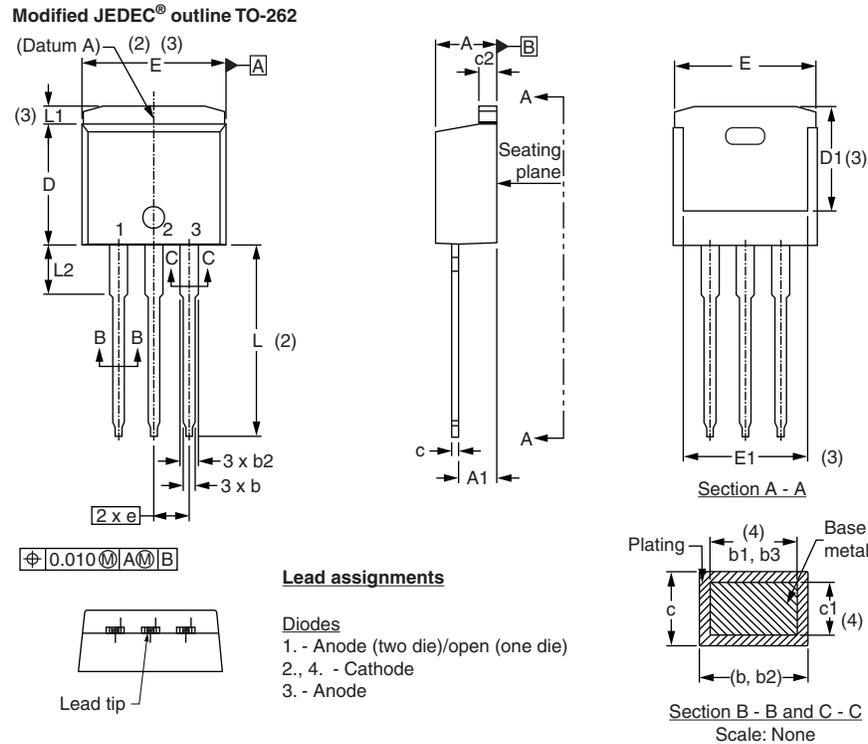
| SYMBOL | MILLIMETERS | | INCHES | | NOTES | SYMBOL | MILLIMETERS | | INCHES | | NOTES |
|--------|-------------|-------|--------|-------|-------|--------|-------------|-------|-----------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. | | | MIN. | MAX. | MIN. | MAX. | |
| A | 4.06 | 4.83 | 0.160 | 0.190 | | D1 | 6.86 | 8.00 | 0.270 | 0.315 | 3 |
| A1 | 0.00 | 0.254 | 0.000 | 0.010 | | E | 9.65 | 10.67 | 0.380 | 0.420 | 2, 3 |
| b | 0.51 | 0.99 | 0.020 | 0.039 | | E1 | 7.90 | 8.80 | 0.311 | 0.346 | 3 |
| b1 | 0.51 | 0.89 | 0.020 | 0.035 | 4 | e | 2.54 BSC | | 0.100 BSC | | |
| b2 | 1.14 | 1.78 | 0.045 | 0.070 | | H | 14.61 | 15.88 | 0.575 | 0.625 | |
| b3 | 1.14 | 1.73 | 0.045 | 0.068 | 4 | L | 1.78 | 2.79 | 0.070 | 0.110 | |
| c | 0.38 | 0.74 | 0.015 | 0.029 | | L1 | - | 1.65 | - | 0.066 | 3 |
| c1 | 0.38 | 0.58 | 0.015 | 0.023 | 4 | L2 | 1.27 | 1.78 | 0.050 | 0.070 | |
| c2 | 1.14 | 1.65 | 0.045 | 0.065 | | L3 | 0.25 BSC | | 0.010 BSC | | |
| D | 8.51 | 9.65 | 0.335 | 0.380 | 2 | L4 | 4.78 | 5.28 | 0.188 | 0.208 | |

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC[®] outline TO-263AB

TO-262

DIMENSIONS in millimeters and inches



| SYMBOL | MILLIMETERS | | INCHES | | NOTES |
|--------|-------------|-------|-----------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. | |
| A | 4.06 | 4.83 | 0.160 | 0.190 | |
| A1 | 2.03 | 3.02 | 0.080 | 0.119 | |
| b | 0.51 | 0.99 | 0.020 | 0.039 | |
| b1 | 0.51 | 0.89 | 0.020 | 0.035 | 4 |
| b2 | 1.14 | 1.78 | 0.045 | 0.070 | |
| b3 | 1.14 | 1.73 | 0.045 | 0.068 | 4 |
| c | 0.38 | 0.74 | 0.015 | 0.029 | |
| c1 | 0.38 | 0.58 | 0.015 | 0.023 | 4 |
| c2 | 1.14 | 1.65 | 0.045 | 0.065 | |
| D | 8.51 | 9.65 | 0.335 | 0.380 | 2 |
| D1 | 6.86 | 8.00 | 0.270 | 0.315 | 3 |
| E | 9.65 | 10.67 | 0.380 | 0.420 | 2, 3 |
| E1 | 7.90 | 8.80 | 0.311 | 0.346 | 3 |
| e | 2.54 BSC | | 0.100 BSC | | |
| L | 13.46 | 14.10 | 0.530 | 0.555 | |
| L1 | - | 1.65 | - | 0.065 | 3 |
| L2 | 3.36 | 3.71 | 0.132 | 0.146 | |

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Vishay products are not designed for use in life-saving or life-sustaining applications or any application in which the failure of the Vishay product could result in personal injury or death unless specifically qualified in writing by Vishay. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.